SCES026H-JULY 1995-REVISED AUGUST 2004

FEATURES

- Member of the Texas Instruments Widebus™
 Family
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- UBT[™] (Universal Bus Transceiver) Combines
 D-Type Latches and D-Type Flip-Flops for
 Operation in Transparent, Latched, Clocked,
 or Clock-Enabled Modes
- B-Port Outputs Have Equivalent 26- Ω Series Resistors, So No External Resistors Are Required
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

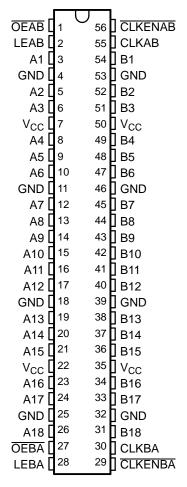
NOTE: For tape-and-reel order entry, the DGGR package is abbreviated to GR.

DESCRIPTION

This 18-bit universal bus transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH162601 combines D-type latches and D-type flip-flops to allow data flow in transparent, latched, clocked, and clock-enabled modes.

DGG OR DL PACKAGE (TOP VIEW)



Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable (CLKENAB and CLKENBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. When OEAB is low, the outputs are active. When OEAB is high, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B, but uses OEBA, LEBA, CLKBA, and CLKENBA.

The B-port outputs include equivalent $26-\Omega$ series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH162601 is characterized for operation from -40°C to 85°C.

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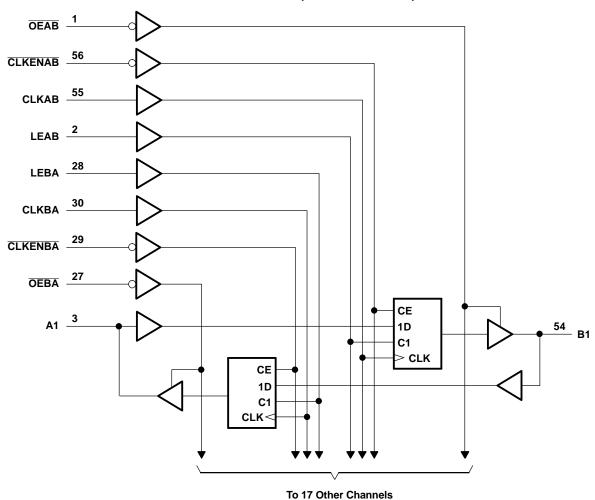


FUNCTION TABLE(1)

	INPUTS							
CLKENAB	OEAB	LEAB	CLKAB	Α	В			
X	Н	Χ	Χ	Χ	Z			
X	L	Н	Χ	L	L			
X	L	Н	Χ	Н	Н			
Н	L	L	Χ	X	B ₀ ⁽²⁾			
н	L	L	Χ	X	B ₀ ⁽²⁾			
L	L	L	\uparrow	L	L			
L	L	L	\uparrow	Н	Н			
L	L	L	L or H	Х	B ₀ ⁽²⁾			

- (1) A-to-B data flow is shown: B-to-A flow is similar, but uses $\overline{\text{OEBA}}$, LEBA, CLKBA, and $\overline{\text{CLKENBA}}$.
- (2) Output level before the indicated steady-state input conditions were established

LOGIC DIAGRAM (POSITIVE LOGIC)





SCES026H-JULY 1995-REVISED AUGUST 2004

ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

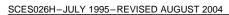
			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	4.6	V
\/	langet valtage garage	Except I/O ports ⁽²⁾	-0.5	4.6	
V _I	Input voltage range	I/O ports ⁽²⁾⁽³⁾	-0.5	V _{CC} + 0.5	V
Vo	Output voltage range ⁽²⁾⁽³⁾	·	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V ₁ < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0	•	-50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V _{CC} of	or GND		±100	mA
	D. d (4)	DGG package		81	0000
θ_{JA}	Package thermal impedance ⁽⁴⁾	DL package		74	°C/W
T _{stg}	Storage temperature range	•	-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

⁽²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

³⁾ This value is limited to 4.6 V maximum.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51.





RECOMMENDED OPERATING CONDITIONS(1)

			MIN	MAX	UNIT	
V _{CC}	Supply voltage		1.65	3.6	V	
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$			
V _{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V	
		V _{CC} = 2.7 V to 3.6 V	2			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8		
V _I	Input voltage	0	V _{cc}	V		
Vo	Output voltage		0	V _{CC}	V	
I _{OH}		V _{CC} = 1.65 V		-4		
	LP at level autout aumout (A a an)	V _{CC} = 2.3 V		-4 -12 -12 -24 -2		
	High-level output current (A port)	V _{CC} = 2.7 V		-12		
		V _{CC} = 3 V		-24	A	
		V _{CC} = 1.65 V		-2	mA	
	Lligh level output ourrent (D.nort)	V _{CC} = 2.3 V		-24 -2 -6 -8		
	High-level output current (B port)	V _{CC} = 2.7 V		-8		
		V _{CC} = 3 V		-12		
		V _{CC} = 1.65 V		4		
	Low-level output current (A port)	V _{CC} = 2.3 V		12		
	Low-level output current (A port)	$V_{CC} = 2.7 \text{ V}$		12		
		V _{CC} = 3 V		A		
OL		V _{CC} = 1.65 V		2	mA	
	Low lovel output ourrent (P. port)	$V_{CC} = 2.3 \text{ V}$		6		
	Low-level output current (B port)	V _{CC} = 2.7 V		8		
		V _{CC} = 3 V		12		
∆t/∆v	Input transition rise or fall rate		10	ns/V		
T _A	Operating free-air temperature		-40	85	°C	

⁽¹⁾ All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCES026H-JULY 1995-REVISED AUGUST 2004

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

P	ARAMETER	TEST CONDITIONS	V _{cc}	MIN TYP(1)	MAX	UNIT
		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2		
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2		
		I _{OH} = -6 mA	2.3 V	2		
	A port		2.3 V	1.7		
		I _{OH} = -12 mA	2.7 V	2.2		
			3 V	2.4		
		I _{OH} = -24 mA	3 V	2		
′он		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2		V
		$I_{OH} = -2 \text{ mA}$	1.65 V	1.2		
		I _{OH} = -4 mA	2.3 V	1.9		
	B port		2.3 V	1.7		
		$I_{OH} = -6 \text{ mA}$	3 V	2.4		0.2 0.45 0.4 0.55 0.2 0.45 0.4 0.55 0.6 0.8 ±5 μΑ ±500 ±10 μΑ 40 μΑ
		I _{OH} = -8 mA	2.7 V	2		
		I _{OH} = -12 mA	3 V	2		
		I _{OL} = 100 μA	1.65 V to 3.6 V		0.2	
		I _{OL} = 4 mA	1.65 V			
		$I_{OL} = 6 \text{ mA}$	2.3 V		0.4	-
	A port		2.3 V		0.7	
		$I_{OL} = 12 \text{ mA}$	2.7 V		0.4	
		I _{OL} = 24 mA	3 V	-1	0.55	
OL	B port	I _{OL} = 100 μA	1.65 V to 3.6 V		0.2	V
<i>J</i> _		$I_{OL} = 2 \text{ mA}$	1.65 V			
		I _{OL} = 4 mA	2.3 V		0.4	
			2.3 V		0.55	1
		$I_{OL} = 6 \text{ mA}$	3 V	-1	0.55	
		I _{OL} = 8 mA	2.7 V			
		I _{OL} = 12 mA	3 V		0.8	
	I .	$V_I = V_{CC}$ or GND	3.6 V		±5	μA
		V _I = 0.58 V		25		
		V _I = 1.07 V	1.65 V	-25		
		V _I = 0.7 V		45		
hold)		V _I = 1.7 V	2.3 V	-45		μA
n(noid)		V _I = 0.8 V		75		•
		V ₁ = 2 V	3 V	-75		
		V _I = 0 to 3.6 V ⁽²⁾	3.6 V	-1	±500	
)Z ⁽³⁾		$V_O = V_{CC}$ or GND	3.6 V	,		μA
CC		$V_1 = V_{CC}$ or GND, $I_0 = 0$	3.6 V			
I _{CC}		One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V		750	<u>μ</u> Α
i	Control inputs	$V_1 = V_{CC}$ or GND	3.3 V	4		pF
io	A or B ports	$V_O = V_{CC}$ or GND	3.3 V	8		pF

All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$. This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to

⁽³⁾ For I/O ports, the parameter I_{OZ} includes the input leakage current.

SCES026H-JULY 1995-REVISED AUGUST 2004



TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

				V _{CC} = 1.8 V		$V_{CC} = 1.8 \text{ V}$ $V_{CC} = 2.5 \text{ V}$ $V_{CC} = 2.7 \text{ V}$		$v_{CC} = 1.8 \text{ V}$ $v_{CC} = 2.5 \text{ V}$ $v_{CC} = 2.7 \text{ V}$ $v_{CC} = 3$ $v_{CC} = 3$		V _{CC} = 3.3 V ± 0.3 V		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency				(1)		140		150		150	MHz
	Dulas duration	LE high		(1)		3.3		3.3		3.3		
l _w	t _w Pulse duration	Pulse duration CLK high or low		(1)		3.3		3.3		3.3		ns
	,	Data before CLK↑		(1)		2.3		2.4		2.1		
	Catum time	Data before LE↓	CLK high	(1)		2		1.6		1.6		ns
t _{su}	Setup time	Data before LEV	CLK low	(1)		1.3		1.2		1.1		
		CLKEN before CL	K↑	(1)		2		2		1.7		
		Data after CLK↑		(1)		0.7		0.7		0.8		
l	Hold time Data after LE↓	Data affaul E	CLK high	(1)		1.3		1.6		1.4		
t _h		Data after LE↓	CLK low	(1)		1.7		2		1.7		ns
		CLKEN after CLK↑	<u> </u>	(1)		0.3		0.5		0.6		

⁽¹⁾ This information was not available at the time of publication.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V	V _{CC} = ± 0.	2.5 V 2 V	V _{CC} = 2.7 V	V _{CC} = ± 0.	3.3 V 3 V	MHz
	(INFOT)	(001701)	MIN TYP	MIN	MAX	MIN MAX	MIN	MAX	
f _{max}			(1)	140		150	150		MHz
	Α	В	(1)	1.3	4.8	5.2	1.6	4.5	
	В	Α	(1)	1	4.3	4.6	1	4.1	
	LEAB	В	(1)	1	5.5	5.9	1.5	5.1	ns
t _{pd}	LEBA	Α	(1)	1	5	5.3	1	4.7	115
	CLKAB	В	(1)	1.5	6.1	6.3	1.6	5.5	
	CLKBA	Α	(1)	1.3	5.6	5.8	1.4	5	
t _{en}	OEAB	В	(1)	1.6	6.1	6.7	1.6	5.7	ns
t _{dis}	OEAB	В	(1)	1.8	5.7	5.3	1.8	4.8	ns
t _{en}	OEBA	Α	(1)	1.1	5.5	6.1	1.1	5.2	ns
t _{dis}	OEBA	Α	(1)	1.3	5.2	4.8	1.6	4.4	ns

⁽¹⁾ This information was not available at the time of publication.

OPERATING CHARACTERISTICS

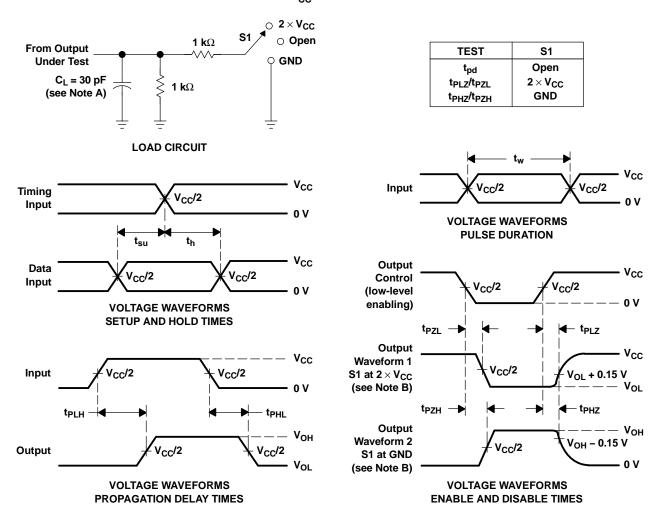
 $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT	
	Power dissipation	Outputs enabled	C ₁ = 50 pF. f = 10 MHz	(1)	41	50	pF
C _{pd}	capacitance	Outputs disabled	$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	(1)	6	6	рг

⁽¹⁾ This information was not available at the time of publication.

SCES026H-JULY 1995-REVISED AUGUST 2004

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V}$

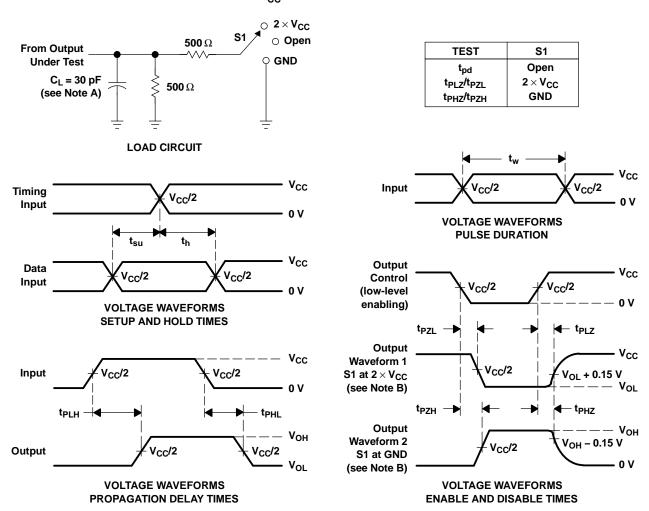


- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z $_{O}$ = 50 $\Omega,\,t_{f}$ \leq 2 ns. t_{f} \leq 2 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. $t_{Pl,7}$ and t_{PH7} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.5 V \pm 0.2 V



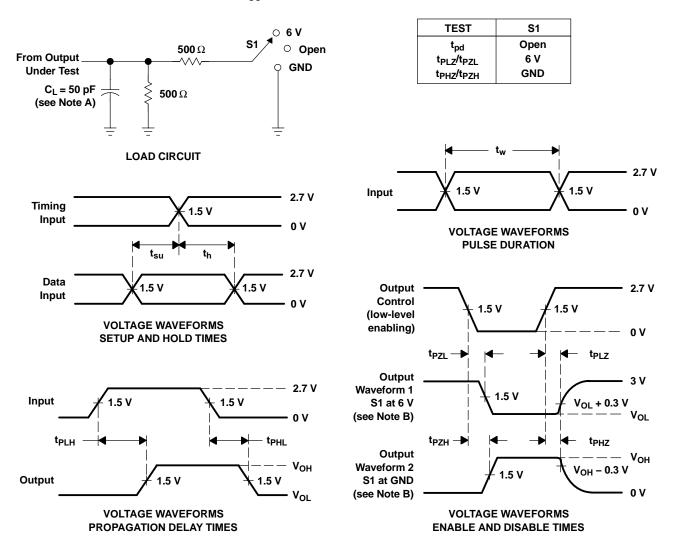
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 2. Load Circuit and Voltage Waveforms

SCES026H-JULY 1995-REVISED AUGUST 2004

PARAMETER MEASUREMENT INFORMATION V_{cc} = 2.7 V AND 3.3 V \pm 0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Ω} = 50 Ω , $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 3. Load Circuit and Voltage Waveforms

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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